



Title of Change:	Planned capacity expansion for eFuse DFN packages, assembly and test in ON Semiconductor's factory in Tarlac, Philippines and assembly in UTAC, Thailand.	
Proposed first ship date for Tarlac Test:	30 June 2017	
Proposed first ship date for Tarlac Assembly:	29 December 2017	
Proposed first ship date for UTAC Assembly:	31 August 2017	
Contact information:	Contact your local ON Semiconductor Sales Office or <ed.pope@onsemi.com>	
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office.	
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>	
Change Part Identification:	DC will identify the supply site	
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines <input checked="" type="checkbox"/> External Foundry/Subcon site(s) UTAC Thai Limited	
Description and Purpose:		
<p>ON Semiconductor is pleased to announce additional capacity expansion for assembly and test at ON Semiconductor's factory in Tarlac, Philippines and assembly in UTAC, Thailand.</p> <p>The Final PCN will detail any lead frame, plating, epoxy, or mold compound changes. There will be no changes to the die or Data Sheet specifications. Existing assembly and test capacity will continue to be available from ON Semiconductor's current factory at Seremban, Malaysia.</p>		
	Before Change Description	After Change Description
Lead Frame	Ag Plated L/F DFN3030	Per FPCN
epoxy	DA AB 841LMISR4 CON	Per FPCN
Mold Compound	MC SU EMEG760	Per FPCN
Wire	1 mil Au	1 mil Au (No change)
Die	CZ4 FAB, no change	CZ4 FAB, no change


Qualification Plan for Assembly:

Test	Specification	Condition	Interval	Lots	Units/Lot
HTOL	JESD22-A108	Ta=125°C, 100% rated Vcc	1008 hrs	3	77
HTRB	JESD22-A108	Ta=125°C, 100% rated Vcc	1008 hrs	3	77
HTSL	JESD22-A103	Ta=150°C	1008 hrs	3	77
TC	JESD22-A104	Ta= -55°C to +150°C	1008 cycles	3	77
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	3	77
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	3	77
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	---	320x3	---
RSH	JESD22-B106	Ta = 265°C, 10 Sec	---	3	10
SD	JSTD002	Ta = 245°C, 10 Sec	---	3	15

Estimated date for Tarlac Test Qualification completion: 30 Jun 2017

Estimated date for Tarlac Assembly Qualification: 29 Dec 2017

Estimated date for UTAC Assembly Qualification: 31 Aug 2017

List of affected Standard Parts:

Part Number	Qualification Vehicle
NIS5132MN1TXG	NIS5132MN1TXG
NIS5132MN2TXG	
NIS5132MN3TXG	
NIS5135MN1TXG	
NIS5135MN2TXG	
NIS5135MN4TXG	